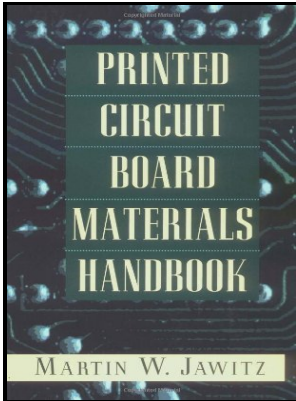


Electronic packaging and interconnection handbook

McGraw-Hill - Electronic Packaging and Interconnection Ser.: Electronic Materials and Processes Handbook by Charles A. Harper (1994, Hardcover) for sale online



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Arab countries -- Politics and government.

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Electronic packaging -- Handbooks, manuals, etc. Electronic packaging and interconnection handbook

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Notes: Includes bibliographical references and index.

This edition was published in 1991



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Electronic Packaging and Interconnection Handbook 4/E : Charles Harper : 9780071430487

Harper is a graduate of the Johns Hopkins University School of Engineering, where he also served as adjunct professor.

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